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1-31-92

Patent & Trademark Office

To the Honorable Commissioner of Patents at

original documents or copy thereof.

102015043

1. Name of conveying party(ies):

INTERNATIONAL BUSINESS MACHINES CORPORATION

North Castle Drive

Armonk, New York, 10504

2. Name and address of receiving party(ies):

Name: JDS UNIPHASE CORPORATION

Address: 210 BAYPOINTE PARKWAY

SAN JOSE, CA 95134

Additional name(s) of conveying party(ies) attached () Yes (X) No

3. Nature of Conveyance:

(X) Assignment

() Merger

() Security Agreement

() Change of Name

() Other

Execution Date: December 27, 2001

Additional name(s) and address(s) attached? () Yes (X) No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent application No.(s)

B. Patent No.(s)

09/852,033

Additional numbers attached? () Yes (X) No

5. Name and address of party to whom correspondence concerning document should be mailed:

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6. Total number of applications and patents involved: [1]

7. Total fee (37 CFR 3.41).....\$ 40.00

[] Enclosed

[X] Authorized to be charged to deposit account.

8. Deposit Account Number:

50-1465

If any additional extension and/or fee is required, or, if any additional fee for claims is required.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Charles E. Wands

Name of Person Signing

Signature

February 20, 2002

Date

Total number of pages including cover sheet, attachments and document: [4]

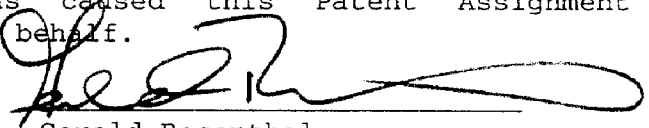
Patent Assignment and Reservation

For good and valuable consideration, the receipt of which is hereby acknowledged, and subject to the reservations stated in a separate written agreement between the parties dated December 19, 2001, and with effect as of December 28, 2001, INTERNATIONAL BUSINESS MACHINES CORPORATION, a New York corporation having a place of business at North Castle Drive, Armonk, New York, 10504, (hereinafter "ASSIGNOR"), hereby grants and assigns to JDS UNIPHASE CORPORATION, a Delaware corporation having a place of business at 210 Baypointe Parkway, San Jose, California, 95134, (hereinafter "ASSIGNEE"), all right, title and interest in and to the United States Letters Patent and applications for United States Letters Patent identified in Exhibits A and B hereto, (hereinafter "ASSIGNED PATENTS"), to have and to hold the same, unto ASSIGNEE for its own use and enjoyment and for the use and enjoyment of its successors and assigns, for the full term or terms of all such rights, subject to any rights, licenses or immunities granted under the ASSIGNED PATENTS to third parties by ASSIGNOR prior to the date hereof.

ASSIGNOR hereby authorizes that all ASSIGNED PATENTS to be issued on or resulting from any of the aforementioned applications for Letters Patent be issued to the ASSIGNEE.

ASSIGNOR hereby reserves and retains, for the benefit of itself and its subsidiary and affiliated companies and its and their successors or assigns, the rights and licenses set forth in the above identified separate written agreement.

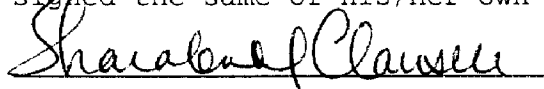
IN WITNESS WHEREOF, ASSIGNOR has caused this Patent Assignment and Reservation to be duly signed on its behalf.


Gerald Rosenthal
Vice President
International Business
Machines Corporation

Dec. 27, 2001
DATE

State of New York)
) S.S.
County of Westchester)

Before me this 27th day of December, 2001, personally appeared Gerald Rosenthal, to me known to be the person who is described in and who signed the foregoing Assignment and acknowledged to me that he/she signed the same of his/her own free will for the purpose therein expressed.


NOTARY PUBLIC

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IBM/JDS Uniphase Patent Assignment Agreement 122801

SHARALEN M. CLAUSELL
A Notary Public, State of New York
No. 01CL5022559
Qualified in Westchester County
My Commission Expires January 18, 2004

PATENT
REEL: 012660 FRAME: 0091

EXHIBIT A**ASSIGNED PATENTS AND PATENT APPLICATIONS**

Patent Number or Application Number	Inventor(s)	Filing Date	Title
6,304,436	Branch, et al.	Oct. 16, 2001	Connector system with outwardly opening door for a removable transceiver module
6,149,465	Berg, et al.	Nov. 21, 2000	Guide rail and CAM system with integrated connector for removable transceiver
6,142,802	Berg, et al.	Nov. 7, 2000	Guide rail and CAM system with integrated connector for removable transceiver
6,074,228	Berg, et al.	Jun. 13, 2000	Guide rail and CAM system with integrated connector for removable transceiver
5,980,324	Berg, et al.	Nov. 9, 1999	Guide rail and CAM system with integrated connector for removable transceiver
5,852,257	Dittman, et al.	Dec. 22, 1998	Optical module with fluxless laser reflow solder joints
5,802,711	Card, et al.	Sept. 8, 1998	Process for making an electrical interconnect structure
5,763,854	Dittman, et al.	May 30, 1996	Machine for laser reflow soldering
5,742,025	Dittman et al.	May 30, 1996	Laser reflow soldering process with lead-tin solder pads
5,663,526	Card, et al.	Sept. 2, 1997	Optical module with tolerant wave soldered joints
5,632,630	Card, et al.	Oct. 19, 1995	Optical module with tolerant wave soldered joints
5,604,831	Dittman, et al.	Feb. 18, 1997	Optical module with fluxless laser reflow solder joints
5,513,073	Block, et al.	Apr. 30, 1996	Optical device heat spreader and thermal isolation apparatus
5,329,428	Block, et al.	Jul. 12, 1994	High-density packaging for multiple removable electronics subassemblies
5,295,214	Card, et al.	Mar. 15, 1994	Optical module with tolerant wave soldered joints
5,202,943	Carden, et al.	Apr. 13, 1993	Optoelectronic assembly with alignment member
09/893812	Chan, et al.		A processing protective plug insert for optical modules
09/852003	Branch, et al.		Module having a latch
09/801320	Branch, et al.		Pull-to-release latch for removable small form factor electronic modules
09/669624	Branch, et al.		Pull type latch mechanism for removable small form factor electronic modules
09/703644	Branch, et al.		Enhanced module kick-out spring mechanism for removable small form factor optical transceiver
09/657214	Branch, et al.		Pull type latch mechanism for removable small form factor electronic modules
09/566012	Branch, et al.		Internal electromagnetic radiation shield with ground cage connection for removable small form factor
09/656086	Gaio, et al.		Electromagnetic radiation grounding shield for optoelectronic components
09/591640	Branch, et al.		Pivoting type latch for removable electronic devices
09/489870	Branch, et al.		Removable small form factor fiber optic transceiver module chassis
09/489184	Branch, et al.		Removable small form factor fiber optic transceiver module and electromagnetic radiation shield
09/410786	Branch, et al.		Removable latch with bezel EMI grounding feature for fiber-optic transceivers
09/410016	Gaio, et al.		Electronic interference shield and ground cage

END OF EXHIBIT A

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IBM/JDS Uniphase Patent Assignment Agreement 122801

**PATENT
REEL: 012660 FRAME: 0092**

EXHIBIT B

ASSIGNED PATENTS

Patent Number	Inventor(s)	Filing Date	Title
6,302,596	Cohen, et al.	Jul 7, 1999	Small form factor optoelectronic transceiver
6,200,041	Gaio, et al.	Dec 8, 1999	Data transfer system incorporating optical fiber link module with internal electromagnetic shield
6,091,750	Paschal, et al.	Mar 25, 1998	Method and Apparatus for Providing Hot Plugging Protection for Laser Optoelectronic devices
6,085,006	Gaio, et al.	Sep 12, 1997	Optical fiber link module with internal electromagnetic shield
5,901,263	Gaio, et al.	Sep 12, 1997	Hot pluggable module Integrated Lock/Extraction Tool
5,631,991	Cohen, et al	Jan 26, 1996	Plastic optical subassemblies for light transfer between an optical fiber and optoelectronic converter and the fabrication of such plastic optical subassemblies
5,537,504	Cina, et al.	Oct 31, 1995	Molded plastic Optical Fiber-Optoelectronic Converter Subassembly
5,511,140	Cina, et al.	Oct 13, 1994	Molded plastic Optical Fiber-Optoelectronic Converter Subassembly
5,329,604	Baldwin, et al.	Feb 11, 1993	Optical fiber coupling device and optoelectronic system utilizing the same
5,005,939	Arvanitakis, et al.	Mar 26, 1990	Optoelectronic assembly
4,912,521	Almquist, et al.	Oct 30, 1987	Electro-optical transducer assembly

END OF EXHIBIT B

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RECORDED: 03/05/2002

PATENT
REEL: 012660 FRAME: 0093